

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STM32H7R7L8H6	25IB*485XXXY	A	9991	23-08-2023
	Amount	UoM	Unit type	ST ECOPACK Grade
	338.00	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant (in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used or other bulk termination : add in comments	NAC	Copper Alloy	SACN305	

Package Designator	Size	Nbr of instances	Shape	
BGA	13x13	225	bulk solder	
Comment	Package : B04V TFBGA 13X13X1.2 225L P 0.80 MM DM00384539			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-10 Jun 2022				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	25IB*485XXX				6000000.0	1000001.9
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	6.999	mg	supplier	die	Silicon (Si)	7440-21-3		6.527	mg	932562	19311
				supplier	metallization	Aluminium (Al)	7429-90-5		0.056	mg	8001	166
				supplier	metallization	Copper (Cu)	7440-50-8		0.175	mg	25004	518
				supplier	metallization	Nickel (Ni)	7440-02-0		0.001	mg	143	3
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.029	mg	4143	86
				supplier	metallization	Titanium (Ti)	7440-32-6		0.005	mg	714	15
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	143	3
				supplier	Passivation	Silicon Oxide	7631-86-9		0.205	mg	29290	607
Substrate (A307790)	M-011 Other inorganic materials	83.886	mg	supplier	BT-substrate	Thermosetting resin (Inorganic filler)	Proprietary		5.033	mg	60000	14891
					BT-substrate	Glass cloth	65997-17-3		22.058	mg	262950	65260
					BT-substrate	Copper foil	7440-50-8		27.557	mg	328500	81528
					Solder mask	Ethanol, 2-(2-ethoxyethoxy)-, 1-acetate	112-15-2		9.689	mg	115500	28665
					Solder mask	Naphtha (petroleum), heavy aromatic	64742-94-5		11.325	mg	135000	33505
					Solder mask	Methanone, (diphenylphosphinyl)(2,4,6-trimethylphenyl)-	75980-60-8		2.810	mg	33500	8314
					Solder mask	TALC (CONTAINING NO ASBESTOS FIBRES)	14807-96-6		3.062	mg	36500	9059
					Solder mask	Dipropylene glycol Methylene Ether Acetate	88917-22-0		2.223	mg	26500	6577
					Solder mask	1,3,5-Triazine-2,4,6-triamine	108-78-1		0.130	mg	1550	385
				DAF (2100AC)	M-011 Other inorganic materials	3.772	mg	supplier	film	Copper (Cu)	7440-50-8	
	film	Silver (Ag)	7440-22-4						0.290	mg	76850	858
	film	2,2-dimethyl-1,3-propanediyl bismethacrylate	1985-51-9						0.139	mg	36900	412
	film	A mixture of: 4-allyl-2,6-bis (2,3-epoxypropyl)phenylmethacrylate	Proprietary						0.101	mg	26900	300
	film	2-[[[2,2-bis[[[1-(oxoallyloxy)methyl]butoxy]methyl]oxy]ethoxy]ethyl]oxy]ethyl methacrylate	94108-97-1						0.098	mg	26000	290
	film	tert-butyl peroxyneodecanoate	26748-41-4						0.019	mg	5000	56
	film	Hydroquinone	123-31-9						0.002	mg	500	6
Bonding wire (Cu)	Precious metals	1.488	mg	supplier	Bonding wire	Gold (Au)	7440-57-5		0.005	mg	3500	15
					Bonding wire	Copper (Cu)	7440-50-8		1.437	mg	965500	4250
					Bonding wire	Palladium (Pd)	7440-05-3		0.046	mg	31000	136
Encapsulation (KE-G1250AAS)	M-011 Other inorganic materials	198.083	mg	supplier	Molding Compound	Epoxy resin	Proprietary		7.923	mg	40000	23442
					Molding Compound	Silica(Fused)	60676-86-0,7631-86-9		178.275	mg	900000	527440
					Molding Compound	Phenol resin	Proprietary		11.093	mg	56000	32818
					Molding Compound	Carbon Black	1333-86-4		0.792	mg	4000	2344
Solder balls (SACN305)	M-011 Other inorganic materials	43.772	mg	supplier	Matte Sn	Tin (Sn)	7440-31-5		42.218	mg	964500	124906
					Matte Sn	Silver (Ag)	7440-22-4		1.313	mg	30000	3885
					Matte Sn	Copper	7440-50-8		0.219	mg	5000	648
					Matte Sn	Nickel	7440-02-0		0.022	mg	500	65